



Product Change Notification: JPZA-03WGWR769

Date:

10-Aug-2026

Product Category:

8-Bit Microcontrollers, Capacitive Touch Sensors, Computing I/O Controllers, Interface- Serial
Peripherals, PoE PD, PoE PSE, Touchscreen Controllers, USB Bridge, Wireless Power And USB-PD
Controller

Notification Subject:

CCB 8435 Initial Notice: Qualification of 558-2C31 as a new die attach material for selected SEC1110, ATMEGA324PHBL, ATMEGA324P, MCP23S18, MCP23018, PIC16F1938, ECE1200, WP200RX01, PIC16F616, WP300RX01, MCP23009, PIC16F1518, MTCH6102, MCP23S09, AT90CAN64, AT90CAN128, AT90CAN32, PD70224, PD69108, PD69104B1, ATMEGA328P, ATMXT144UD-A, ATMXT288UD-A, ATMXT144UD-SL, ATMEGA168, ATTINY861, AT90USB647, AT90USB646, PD69104 and ATMEGA164P device families available in various packages at NSEB and UTL3 assembly sites.

Affected CPNs:

[JPZA-03WGWR769_Affected_CPN_08102026.pdf](#)
[JPZA-03WGWR769_Affected_CPN_08102026.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of 558-2C31 as a new die attach material for selected SEC1110, ATMEGA324PHBL, ATMEGA324P, MCP23S18, MCP23018, PIC16F1938, ECE1200, WP200RX01, PIC16F616, WP300RX01, MCP23009, PIC16F1518, MTCH6102, MCP23S09, AT90CAN64, AT90CAN128, AT90CAN32, PD70224, PD69108, PD69104B1, ATMEGA328P, ATMXT144UD-A, ATMXT288UD-A, ATMXT144UD-SL, ATMEGA168, ATTINY861, AT90USB647, AT90USB646, PD69104 and ATMEGA164P device families available in various packages at NSEB and UTL3 assembly sites.

Pre and Post Summary Changes:

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: August 10, 2026: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_JPZA-03WGWR769_Qualification_Plan.pdf
PFAS Elimination and Die Attach Explanation.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

AT90CAN64-16MUR
AT90CAN128-15MT
AT90CAN128-16MU
AT90CAN128-16MUR
AT90CAN32-15MT1
PD70224LILQ-TR
AT90CAN64-15MZ
PD69108ILQ-TR
PD69108FILQ-TR
AT90CAN32-15MZ
ATMXT144UD-AMBSLI2CVA1
ATMXT144UD-AMBI2CVAO
ATMXT144UD-AMBSPIVAO
ATMXT288UD-AMBI2CVAO
ATMXT288UD-AMBSPIVAO
ATMXT144UD-AMBRSPIVA1
ATMXT288UD-AMBRI2CVA1
ATMXT288UD-AMBRSPIVA1
ATMXT144UD-AMBRI2CVA1
ATMXT144UD-AMBRSLI2CVAO
SEC1110-A5-02NC
SEC1110-A5-02
SEC1110-A5-02G1
SEC1110-A5-03G1
SEC1110-A5-04G1
SEC1110-A5-05G1
SEC1110I-A5-02
SEC1110I-A5-02G1
SEC1110-A5-02NC-TR
SEC1110-A5-02-TR
SEC1110I-A5-02-TR
SEC1110-1100A5

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ATMEGA324PHBL-B15MT

ATMEGA324P-B15MZ

MCP23S18T-E/MJVAO

MCP23018-E/MJVAO

MCP23018T-E/MJVAO

PIC16LF1938-E/MV

PIC16LF1938-I/MV

PIC16LF1938-I/MVC02

PIC16LF1938T-I/MV

PIC16LF1938T-I/MVC02

PIC16LF1938T-I/MVC03

PIC16LF1938T-E/MV

ECE1200-I/LD

WP200RX01-E/ML001

PIC16F616-E/ML

WP300RX01-I/ML01C00

PIC16F616-I/ML

PIC16F616-H/ML

PIC16F616T-I/ML034

PIC16F616T-I/ML

PIC16F616T-E/ML

MCP23009-E/MG

MCP23009T-E/MG

PIC16LF1518-E/MV

MTCH6102-I/MV

PIC16LF1518-I/MV

MTCH6102T-I/MV

PIC16LF1518T-I/MV

MCP23S18-E/MJ

MCP23S18T-E/MJ

MCP23018-E/MJ

MCP23018T-E/MJ

MCP23S09-E/MG

MCP23S09T-E/MG

PD69104B1ILQ-TR

PD69104B1FILQ-TR

ATMEGA328P-15MZ

AT90CAN64-15MT

ATMXT144UD-AMTSPIVA1

ATMXT288UD-AMTI2CVA1

ATMXT288UD-AMTSPIVA1

ATMXT144UD-AMTI2CVA1

ATMXT144UD-AMTSLI2CVAO

ATMXT144UD-AMTI2CVAO

ATMXT144UD-AMTSPIVAO

ATMXT288UD-AMTI2CVAO

ATMXT288UD-AMTSPIVAO

ATMXT144UD-AMBSPIVA1

ATMXT288UD-AMBI2CVA1

ATMXT288UD-AMBSPIVA1

ATMXT144UD-AMBI2CVA1

ATMXT144UD-AMBSLI2CVAO

ATMXT288UD-AMBRSPIVAO

ATMXT144UD-AMTRSPIVA1

ATMXT288UD-AMTRI2CVA1

ATMXT288UD-AMTRSPIVA1

ATMXT144UD-AMTRI2CVA1

ATMXT144UD-AMTRSLI2CVAO

ATMXT144UD-AMTRI2CVAO

ATMXT144UD-AMTRSPIVAO

ATMXT288UD-AMTRI2CVAO

ATMXT288UD-AMTRSPIVAO

ATMEGA168-15MZT

AT90CAN128-15MT1

ATTINY861-15MZ

AT90CAN128-15MZ

AT90CAN64-15MT1

AT90USB647-MU

AT90USB646-MU

AT90USB647-MUR

AT90USB646-MUR

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AT90CAN32-15MT

AT90CAN32-16MU

AT90CAN32-16MUR

ATMEGA164P-B15MZ

ATMXT144UD-AMBRSLI2CVA1

ATMXT144UD-AMBRI2CVAO

ATMXT144UD-AMBRSPIVAO

ATMXT288UD-AMBRI2CVAO

AT90CAN64-16MU

AT90CAN64-16MU-HCM



QUALIFICATION PLAN SUMMARY

PCN#: JPZA-03WGWR769

DATE:
July 30, 2026

**Qualification of 558-2C31 as a new die attach material for selected
SEC1110, ATMEGA324PHBL, ATMEGA324P, MCP23S18,
MCP23018, PIC16F1938, ECE1200, WP200RX01, PIC16F616,
WP300RX01, MCP23009, PIC16F1518, MTCH6102, MCP23S09,
AT90CAN64, AT90CAN128, AT90CAN32, PD70224, PD69108,
PD69104B1, ATMEGA328P, ATMXT144UD-A, ATMXT288UD-A,
ATMXT144UD-SL, ATMEGA168, ATTINY861, AT90USB647,
AT90USB646, PD69104 and ATMEGA164P device families
available in various packages at NSEB and UTL3 assembly sites.
This is a Q006 Grade 1 qualification.**

Purpose: Qualification of 558-2C31 as a new die attach material for selected SEC1110, ATMEGA324PHBL, ATMEGA324P, MCP23S18, MCP23018, PIC16F1938, ECE1200, WP200RX01, PIC16F616, WP300RX01, MCP23009, PIC16F1518, MTCH6102, MCP23S09, AT90CAN64, AT90CAN128, AT90CAN32, PD70224, PD69108, PD69104B1, ATMEGA328P, ATMXT144UD-A, ATMXT288UD-A, ATMXT144UD-SL, ATMEGA168, ATTINY861, AT90USB647, AT90USB646, PD69104 and ATMEGA164P device families available in various packages at NSEB and UTL3 assembly sites. This is a Q006 Grade 1 qualification.

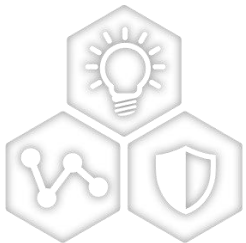
CCB No.: 8435

Misc.	Assembly site	NSEB (UTL-1) & UTL3
	BD Number	BD-004623 rev.01
	MP Code (MPC)	355T4YTLBC01
	Part Number (CPN)	AT90CAN32-15MZ
	MSL information	MSL-3 @260C
	Assembly Shipping Media (T/R, Tube/Tray)	T/R
	Base Quantity Multiple (BQM)	4,000 units
	Reliability Site	MPHIL
Lead-Frame	Paddle size	264x264 mil
	Material	EFTEC-64T
	DAP Surface Prep	COPPER (Ag ring)
	Treatment	In house roughening
	Process	Etch
	Lead-lock (Locking Hole, Half Etched, Dimple, etc. If none, please put No or N/A)	Dimple
	Part Number	FR0160
	Lead Plating	Matte Tin
	Strip Size	250x70 mm
	Strip Density	120 unit/strip
Bond Wire	Material	CuPdAu
Die Attach	Part Number	558-2C31
	Conductive	Yes
MC	Part Number	G700LTD
PKG	Package Type	VQFN
	Pin/Ball Count	64
	PKG width/size	9x9x1mm

Eliminating PFAS from Microchip ICs



A Leading Provider of Smart, Connected and Secure Embedded Control Solutions



SMART | CONNECTED | SECURE

Microchip
August 2025

Eliminating PFAS from MCHP ICs

- **What is PFAS**
- **Microchip's Environmental Stewardship**
- **Microchip Products with PFAS**
- **Time Frame to PFAS-Free Die Attach**
- **What is Die Attach**
- **Will clients be required to switch to PFAS free products**
- **Risk Assessment**

What is PFAS: Poly(Per) FluoroAlkyL Substances (PFAS)

Poly(Per) FluoroAlkyL Substances (PFAS)

- There may be 12,000 or more PFAS chemicals that are used in small amounts in many different items
 - PFAS can be in the product itself.
 - PFAS can also be used to manufacture products while not in the product itself

PFAS is the new “buzzword” throughout many industries

- Often nicknamed “forever chemicals” because once released into the environment, it never degrades and will accumulate over time
- As PFAS accumulates in the environment over long periods of time, there can be increasing toxicity and polluting effects
- Therefore, government agencies around the globe are considering legislation toward removal of PFAS although PFAS legislations are not fully defined yet

Microchip's Environmental Stewardship

Although very few laws have been enacted regarding PFAS to date, there is a rapidly growing movement among governments around the world to eliminate PFAS

- Initial legislation has targeted on clothing and food products
- Additional legislation and their timings continue to evolving

Companies such as Microchip, which are committed to addressing contaminants in water, air, food, and living organisms, are proactively working to remove PFAS even in the absence of specific legal requirements.

Microchip's suppliers are also taking proactive steps to eliminate PFAS chemicals from the materials they provide to Microchip.

Microchip believes it is prudent to take immediate action toward offering PFAS-free products to all clients, regardless of application, industry, country, or current regulatory requirements.

Achieving “PFAS-Free” status may serve as a competitive advantage for both Microchip and its clients.

Microchip products with PFAS

The primary material in Microchip products containing PFAS is known as die attach. PFAS-free die attach is not new to either Microchip or the industry; in fact, Microchip has shipped hundreds of millions of units utilizing PFAS-free die attach.

Both PFAS and PFAS-free die attach materials are currently in use because PFAS was not previously identified as a substance of concern.

The change announced in this Product Change Notification (PCN) for Microchip-owned factories involves transitioning to the same PFAS-free die attach that has already been qualified and used in other products.

Time Frame to PFAS-Free Die Attach

Qualification of products assembled at Microchip-owned factories has been completed.

While inventory containing PFAS die attach will continue to be shipped, the implementation of PFAS-free die attach in the assembly process is scheduled to begin as early as September 3, 2025.

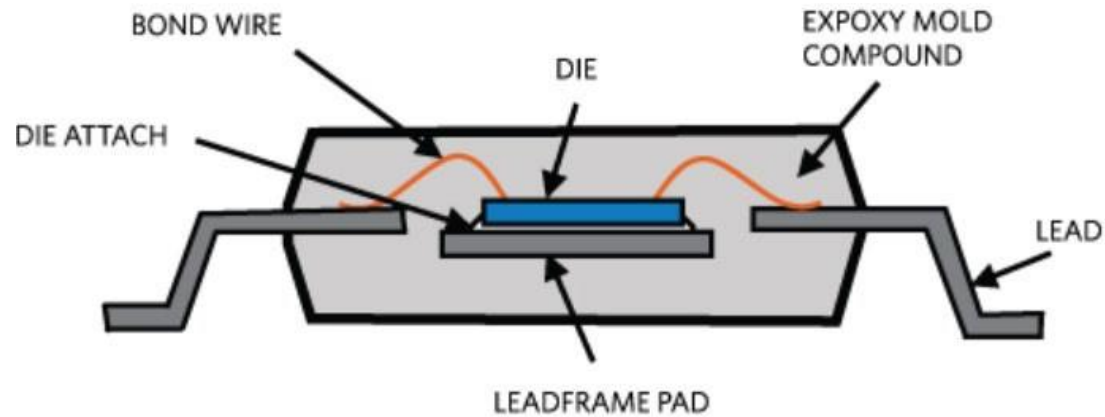
Microchip will consume all existing inventory and die attach, so the exact implementation date will depend on when current inventories are depleted.

- For PPAP clients IMDS/CAMDS material content declarations will be updated.

Schedules for assembly locations not owned by Microchip (subcontractors or "subcons") are currently under review. We anticipate a similar mix of products already utilizing both PFAS and PFAS-free die attach at these locations.

Product Change Notifications (PCNs) announcing die attach changes at subcontractor sites will be issued once schedules are finalized. We expect these timelines to be similar to those for our internal factories.

What is die attach



A thin layer of epoxy between the silicon die and copper pad portion of the lead frame.

- Holds the die in place during the wire bond and mold encapsulation processes
- The bottom of the die has no transistors or active circuits.
- The interface is identical regardless of device type, fab location, technology node, wire material etc.
- **Therefore, allows extremely broad range of products to be grouped into a single qualification.**

Will Clients be required to switch to PFAS-Free Products

The timeline for legislation to eliminate PFAS chemicals remains uncertain; however, regulatory action is anticipated.

Suppliers of PFAS chemicals and raw materials containing PFAS are already announcing end-of-life plans in advance of any formal legislation.

It is expected that suppliers will discontinue offering die attach materials containing PFAS within the next two years, regardless of when government regulations take effect.

While Microchip is committed to providing as much transition time as possible for our clients, we strongly encourage you to begin planning now to avoid potential supply interruptions.

Risk Assessment:



Microchip does not anticipate that this change will impact our clients for the following reasons:

- Microchip has been using PFAS-free die attach material for several years.
- We have shipped hundreds of millions of units utilizing this material without incident.
- Die Attach is not application relevant.

Given these factors, Microchip believes there is minimal cause for concern regarding this change, and additional client qualifications would be redundant and time-consuming. However, if you have any questions that are not addressed in the PCN or this presentation, please do not hesitate to contact us.

